

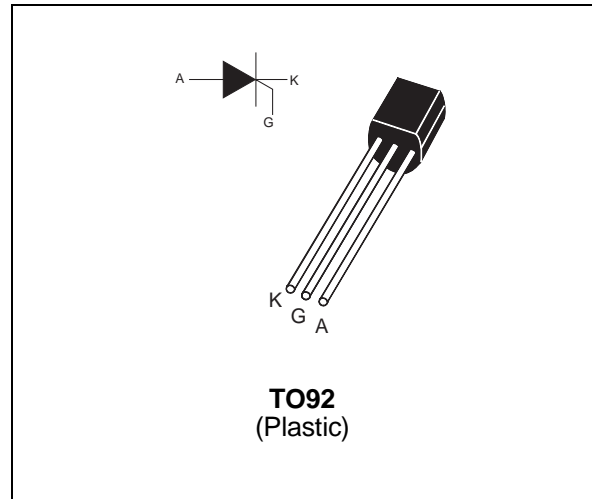
SENSITIVE GATE SCR

FEATURES

- $I_{T(RMS)} = 0.8A$
- Sensitive gate : $I_{GT} < 200 \mu A$
- $V_{DRM}/V_{RRM} = 600 V$
- Low holding current : $I_H < 5 mA$

DESCRIPTION

The X00602MA SCR uses a high performance glass passivated PNP technology. This device is perfectly suited for applications requiring very low gate sensitivity such as sensors, detectors, pilot for larger thyristors, Ground Fault Interruptor (GFI), small motor control, relay drivers, etc...



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V_{DRM} V_{RRM}	Repetitive peak off-state voltage $R_{GK} = 1K\Omega$	$T_j = 125^\circ C$	600	V
$I_{T(RMS)}$	RMS on-state current (180° conduction angle)	$T_I = 85^\circ C$	0.8	A
$I_{T(AV)}$	Average on-state current (180° conduction angle)	$T_I = 85^\circ C$	0.5	A
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = $25^\circ C$)	$t_p = 8.3 ms$	10	A
		$t_p = 10 ms$	9	
I^2t	I^2t Value for fusing	$t_p = 10 ms$	0.5	A^2s
di/dt	Critical rate of rise of on-state current $I_G = 10 mA$ $di_G/dt = 0.1 A/\mu s$.		50	$A/\mu s$
T_{stg} T_j	Storage temperature range Operating junction temperature range		- 40, + 150 - 40, + 125	$^\circ C$
T_I	Maximum lead temperature for soldering during 10s at 2mm from case		260	$^\circ C$

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth(j-a)	Junction to ambient	150	°C/W
Rth(j-l)	Junction to lead for DC	70	°C/W

GATE CHARACTERISTICS

$P_{G(AV)} = 0.1W$ $P_{GM} = 2W$ ($t_p = 20\mu s$) $I_{GM} = 1A$ ($t_p = 20\mu s$)

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Value	Unit
I_{GT}	$V_D = 12V$ (DC) $R_L = 140\Omega$	$T_j = 25^\circ C$	MAX	200	μA
V_{GT}	$V_D = 12V$ (DC) $R_L = 140\Omega$	$T_j = 25^\circ C$	MAX	0.8	V
V_{GD}	$V_D = V_{DRM}$ $R_L = 33K\Omega$ $R_{GK} = 1K\Omega$	$T_j = 125^\circ C$	MIN	0.2	V
V_{RG}	$I_{RG} = 10\mu A$	$T_j = 25^\circ C$	MIN	5	V
I_H	$I_T = 50mA$ $R_{GK} = 1K\Omega$	$T_j = 25^\circ C$	MAX	5	mA
I_L	$I_G = 500\mu A$ $R_{GK} = 1K\Omega$	$T_j = 25^\circ C$	MAX	6	mA
V_{TM}	$I_{TM} = 1A$ $t_p = 380\mu s$	$T_j = 25^\circ C$	MAX	1.35	V
I_{DRM} I_{RRM}	$V_D = V_{DRM}$ $R_{GK} = 1K\Omega$ $V_R = V_{RRM}$	$T_j = 25^\circ C$	MAX	1	μA
		$T_j = 125^\circ C$	MAX	100	μA
dV/dt	$V_D = 67\%V_{DRM}$ $R_{GK} = 1K\Omega$	$T_j = 125^\circ C$	MIN	25	V/ μs

ORDERING INFORMATION

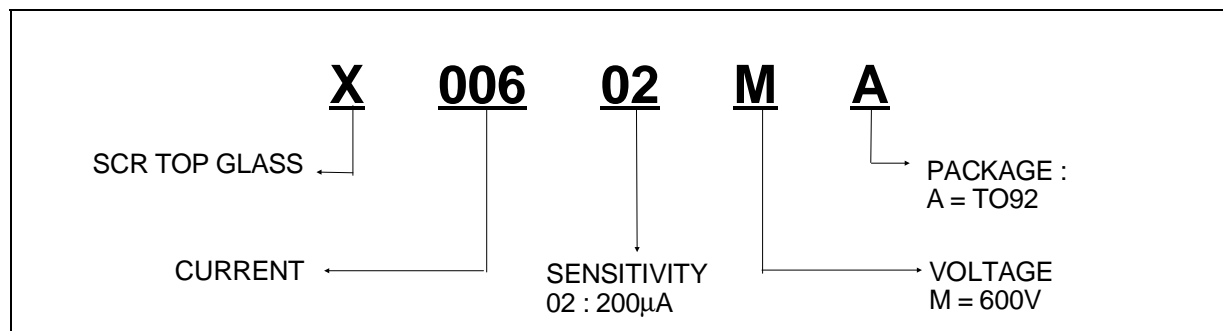


Fig. 1: Maximum average power dissipation versus average on-state current.

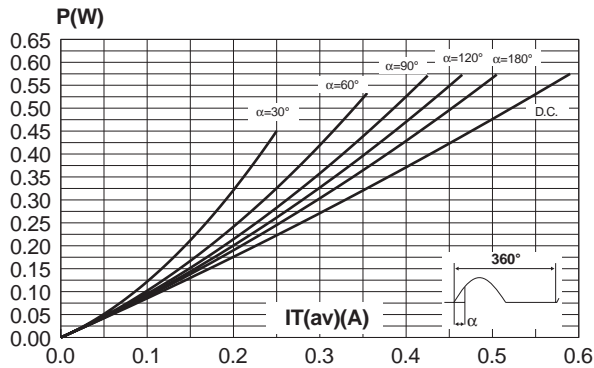


Fig. 2: Correlation between maximum average power dissipation and maximum allowable temperature (T_{amb} and T_{lead}).

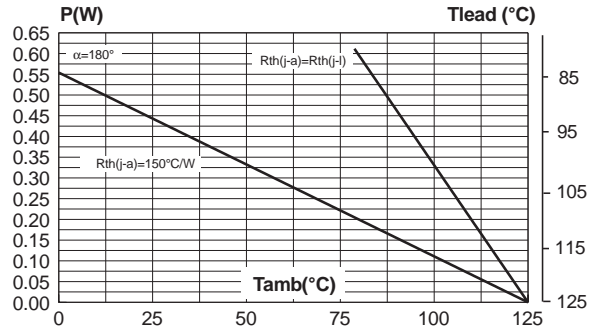


Fig. 3-1: Average and D.C on-state current versus lead temperature.

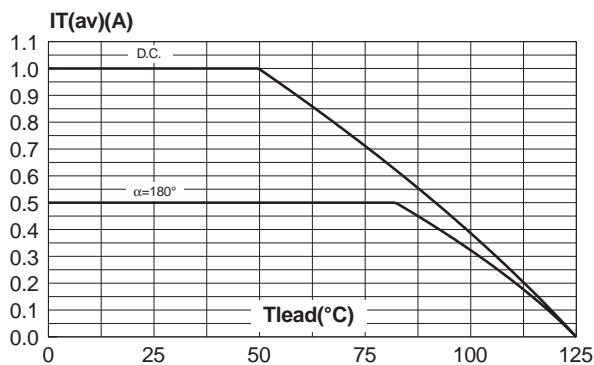


Fig. 3-2: Average and D.C on-state current versus ambient temperature (device mounted on FR4 with recommended pad layout).

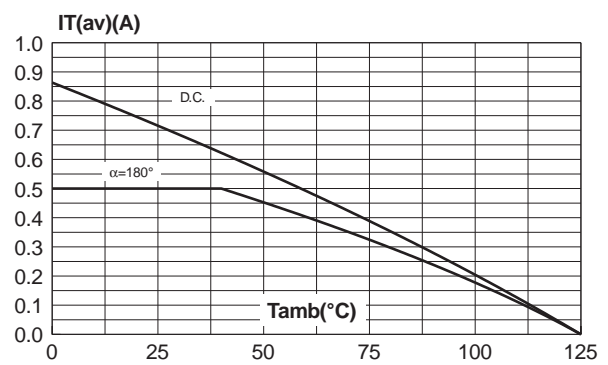


Fig. 4: Relative variation of thermal impedance junction to ambient versus pulse duration.

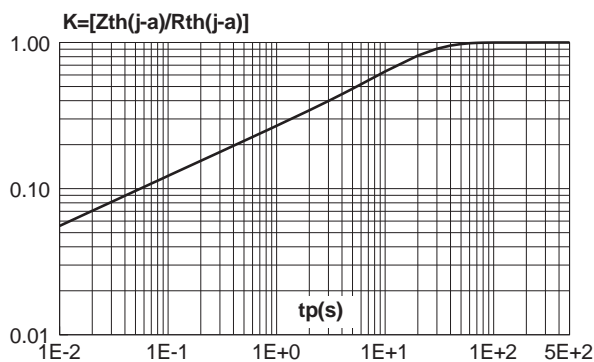
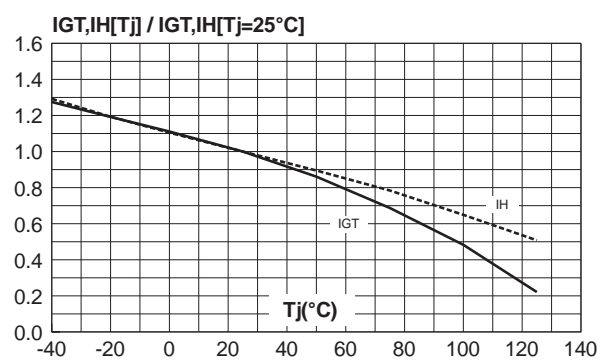


Fig. 5: Relative variation of gate trigger current and holding current versus junction temperature.



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Fig. 6: Relative variation of holding current versus gate-cathode resistance (typical values).

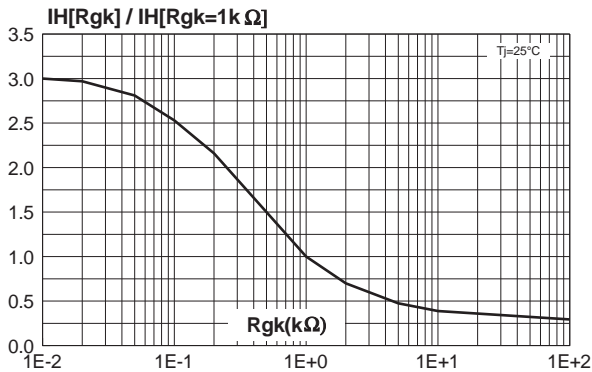


Fig. 7: Relative variation of dV/dt immunity versus gate-cathode resistance (typical values).

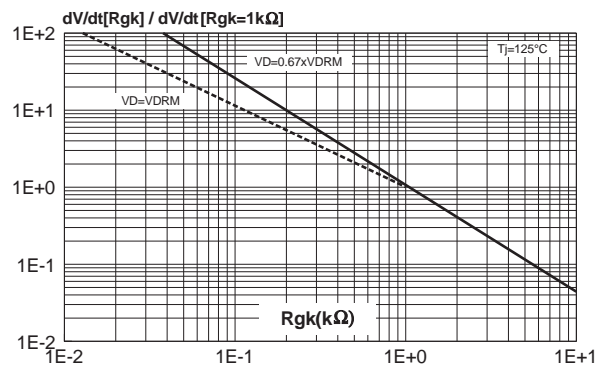


Fig. 8: Relative variation of dV/dt immunity versus additional gate-cathode capacitance (typical values).

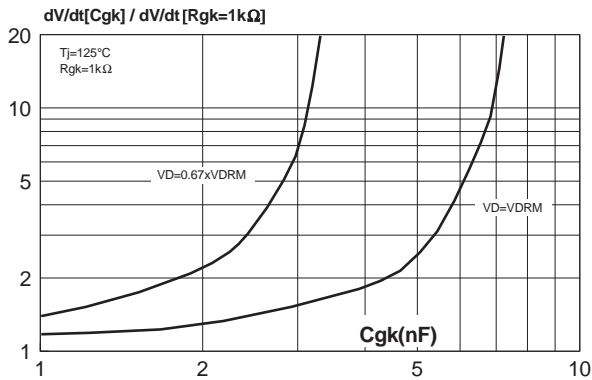


Fig. 9: Non repetitive surge peak on-state current versus number of cycles.

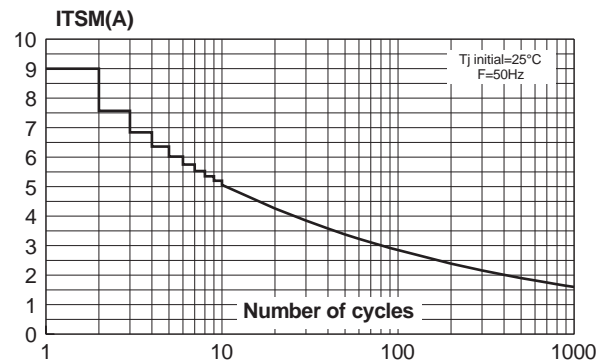


Fig. 10: Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t_p \leq 10ms$, and corresponding value of I^2t .

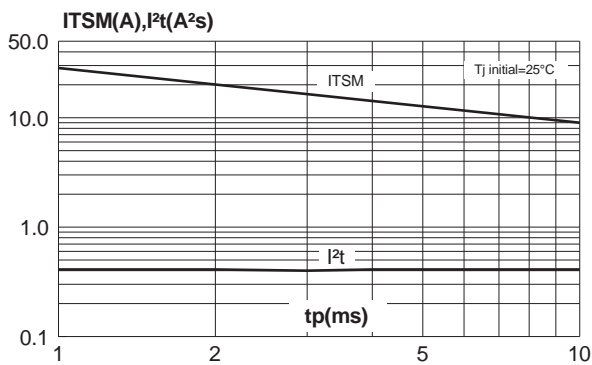
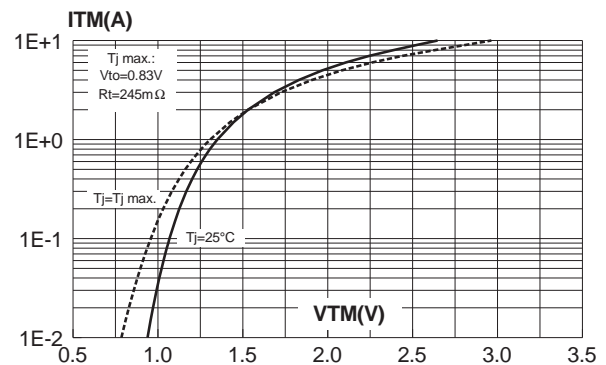


Fig. 11: On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA

TO92 (Plastic)

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A		1.35			0.053	
B			4.70			0.185
C		2.54			0.100	
D	4.40			0.173		
E	12.70			0.500		
F			3.70			0.146
a			0.45			0.017

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
X00602MA 1AA2	X0602MA	TO92	0.2g.	2500	Bulk
X00602MA 2AL2	X0602MA	TO92	0.2g.	2000	Ampopack

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